

1 **In the Claims:**

2 Claims 89, 90, and 98-111 were pending at the time of the Office Action.

3 Claims 89 and 90 were previously withdrawn from consideration.

4 Claims 98-111 are rejected.

5 Please cancel claims 89, 90 and 98-111 without prejudice.

6 Please add new claims 112-122 as indicated below in the listing of claims.

7 Accordingly, claims 112-122 are pending.

8
9 **Listing of Claims:**

10
11 **Claims 1-111** (Canceled)

12
13 **112.** (New) A chip socket assembly comprising:

14 a chip package having a contact side, the contact side comprising a plurality
15 of compliant contacts, the contacts adapted for detachable electrical coupling to a
16 circuit board, the chip package having second and third sides formed with
17 oppositely disposed protrusions;

18 an integrated circuit disposed within the chip package, the integrated circuit
19 electrically coupled to the plurality of compliant contacts; and

20 a base formed with oppositely disposed clip portions to receive the chip
21 package, the clip portions formed with sockets to detachably engage the chip
22 package protrusions.
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1 **113.** (New) The chip socket assembly of claim 112, wherein the contacts
2 are adapted for direct engagement to the circuit board.

3
4 **114.** (New) The chip socket assembly of claim 112, further including an
5 elastomeric connector, the elastomeric connector interposed between the circuit
6 board and the base, and wherein the contacts are adapted for engaging the
7 elastomeric connector.

8
9 **115.** (New) The chip socket assembly of claim 114, wherein the contacts
10 are compressible and the elastomeric connector is cylindrical, providing spring
11 force when the contacts are compressed.

12
13 **116.** (New) The chip socket assembly of claim 112, wherein the contacts
14 are compressible and the contact side of the chip package is extended to form a
15 pocket into which the contacts extend when compressed.

16
17 **117.** (New) The chip socket assembly of claim 112, further comprising:
18 a pin extending from the chip package; and
19 a slotted guide in the base configured to receive the pin and guide the chip
20 package into the base.

21
22 **118.** (New) The chip socket assembly of claim 112, wherein the contacts
23 are substantially C-shaped.

1 **119.** (New) The chip socket assembly of claim 112, wherein the contacts
2 comprise beryllium-copper.

3
4 **120.** (New) The chip socket assembly of claim 112, wherein the chip
5 package comprises a flexible material.

6
7 **121.** (New) The chip socket assembly of claim 112, wherein the chip
8 package comprises silicone rubber.

9
10 **122.** (New) The chip socket assembly of claim 112, wherein the
11 integrated circuit is flexible.